# CRAY T916 MAINFRAME CHASSIS SITE PLANNING AND PREPARATION

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## **Specifications**

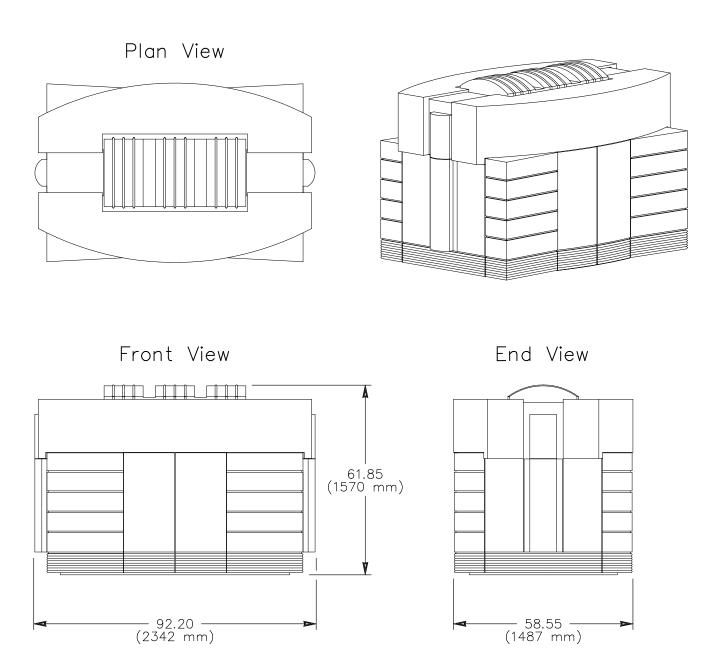
The CRAY T916 mainframe chassis is a dielectric-cooled computer that contains many electronic components such as logic modules and power supplies.

Table 1 provides the specifications for the CRAY T916 mainframe chassis. Refer to Figure 1 for an illustration of the CRAY T916 chassis.

Table 1. CRAY T916 Mainframe Chassis Specifications

Characteristic	Specification
Height	61.85 in. (1,570 mm)
Width	92.20 in. (2,342 mm)
Depth	58.55 in. (1,487 mm)
Weight	9,285 lbs (4,212 kg)
Access requirements: Sides Top	36.00 in. (914 mm) on all sides 32.00 in. (813 mm)
Cooling requirement	Dielectric coolant
Heat dissipation to air	Negligible
Input voltage supplied by the HVDC-160	Six 330-Vdc power circuits One 120-Vac control circuit
Input wiring connections	Compression lugs

Figure 1. CRAY T916 Mainframe Chassis



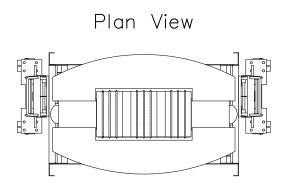
## **Shipping Configuration**

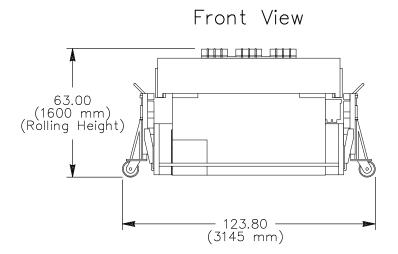
The CRAY T916 chassis is shipped as a single unit on Cray Research-provided lifts. Table 2 provides the CRAY T916 chassis shipping configuration specifications. Refer to Figure 2 for an illustration of the shipping configuration.

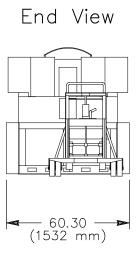
Table 2. CRAY T916 Chassis Shipping Configuration Specifications

Characteristic	Specification
Height	63.00 in. (1,600 mm)
Width	123.80 in. (3,145 mm)
Depth	60.30 in. (1,532 mm)
Weight	6,363 lbs (2,886 kg)

Figure 2. CRAY T916 Mainframe Chassis Shipping Configuration







### **Floor Preparation**

Prior to system delivery, you must prepare the raised floor for the CRAY T916 chassis installation. Cray Research recommends a minimum clearance of 18.00 in. (457 mm) between the subfloor and the underside of the raised-floor panels. Clearances of less than 18.00 (457 mm) must be reviewed by Cray Research site planning personnel.

You must also prepare the seven floor cutouts and install a minimum of nine additional floor support pedestals. Floor cutouts provide an opening for data, power, and dielectric-coolant connections. To prevent damage to system connections, these floor cutouts must be free of sharp edges and burrs.

**NOTE:** Cray Research provides full-scale templates used to prepare the chassis floor cutouts and to show floor support pedestal locations.

Refer to Figure 3 for an illustration of the floor cutouts and additional floor support pedestal locations for the CRAY T916 chassis.

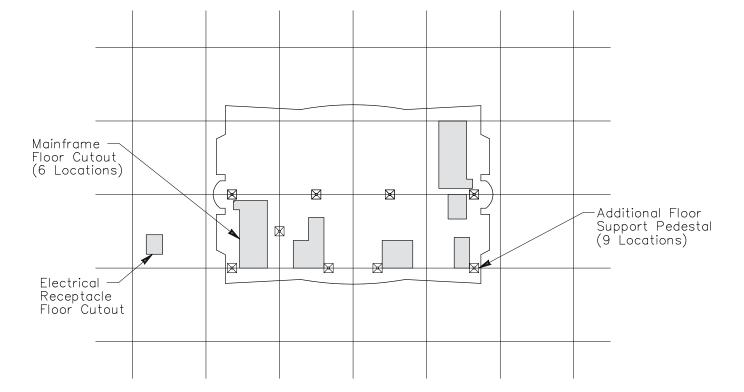


Figure 3. CRAY T916 Floor Cutouts and Additional Floor Support Pedestal Locations

### **Power Wiring Requirements**

You must provide and install the following power and control wiring for the CRAY T916 mainframe chassis:

- Six 330-Vdc, 100-A circuits from the 160-kW high-voltage DC (HVDC-160) cabinet to the mainframe chassis.
   The recommended minimum wire size is #2 AWG (35 mm²).
- One 120-Vac, 50/60-Hz, single-phase, 10-A circuit from the HVDC-160 to the mainframe chassis for control power. The recommended minimum wire size is #14 AWG (2.5 mm<sup>2</sup>).
- One 120-Vac, 50/60-Hz, single-phase, 10-A circuit from the HVDC-160 to the mainframe chassis for maintenance. The recommended minimum wire size is #14 AWG (2.5 mm<sup>2</sup>).